SYSTEM AND METHOD FOR INSPECTION OF SEMICONDUCTOR PACKAGES

Abstract

A system and method for inspection of semiconductor packages. The system comprises a lighting assembly, a prism assembly, a first camera and a second camera. The prism assembly comprises a number of surfaces. Light reflected off the semiconductor package positioned at a ready position enters the prism assembly before exiting therefrom and entering into one of the first camera and the second camera. The first camera and the second camera have different magnifications. The first camera captures an image of a bottom surface and each of four side surfaces of the semiconductor package. The second camera captures an image of only the bottom surface of the semiconductor package. Light supplied by the lighting assembly is of a predetermined set of properties, which are variable to enhance specific defect detection. Images captured by the first camera and the second camera are transferred to a controller for analysis thereby.

Figure 1